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July 2014

FDMA1027P

Dual P-Channel PowerTrench® MOSFET

General Description

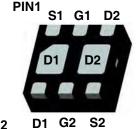
This device is designed specifically as a single package solution for the battery charge switch in cellular handset and other ultra-portable applications. It features two independent P-Channel MOSFETs with low on-state resistance for minimum conduction losses. When connected in the typical common source configuration, bi-directional current flow is possible.

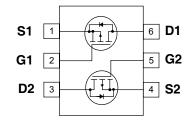
The MicroFET 2x2 package offers exceptional thermal performance for it's physical size and is well suited to linear mode applications.

Features

- -3.0 A, -20V. $R_{DS(ON)} = 120 \text{ m}\Omega$ @ $V_{GS} = -4.5 \text{ V}$
 - $R_{DS(ON)} = 160 \text{ m}\Omega$ @ $V_{GS} = -2.5 \text{ V}$
 - $R_{DS(ON)} = 240 \text{ m}\Omega$ @ $V_{GS} = -1.8 \text{ V}$
- Low Profile 0.8 mm maximun in the new package MicroFET 2x2 mm
- RoHS Compliant
- Free from halogenated compounds and antimony oxides







MicroFET 2X2

Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	MOSFET Drain-Source Voltage		-20	V
V _{GSS}	MOSFET Gate-Source Voltage		±8	V
1	Drain Current -Continuous	(Note 1a)	-3.0	A
'D	-Pulsed		-6	7 ^
	Power dissipation	(Note 1a)	1.4	
P _D	·	(Note 1b)	0.7	14/
		(Note 1c)	1.8	─ w
		(Note 1d)	0.8	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance for Single Operation, Junction-to-Ambient	(Note 1a)	86	
$R_{\theta JA}$	Thermal Resistance for Single Operation, Junction-to-Ambient	(Note 1b)	173	°C/W
$R_{\theta JA}$	Thermal Resistance for Dual Operation, Junction-to-Ambient	(Note 1c)	69	1 0/00
$R_{\theta JA}$	Thermal Resistance for Dual Operation, Junction-to-Ambient	(Note 1d)	151	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape Width	Quantity
027	FDMA1027P	7"	8mm	3000 units

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	-20	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = -250\mu A$, Referenced to 25°C	-	-12	-	mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -16V, V _{GS} = 0V	-	-	-1	μА
I _{GSS}	Gate-Body Leakage,	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	-	-	±100	nA

On Characteristics (Note 2)

V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.4	-0.7	-1.3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250\mu A$, Referenced to 25°C	-	2	-	mV/°C
		$V_{GS} = -4.5V, I_D = -3.0A$	-	90	120	
		$V_{GS} = -2.5V, I_D = -2.5A$	-	120	160	
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = -1.8V, I_D = -1.0A$	-	172	240	mΩ
		$V_{GS} = -4.5V, I_D = -3.0A$ $T_J = 125^{\circ}C$	-	118	160	
I _{D(on)}	On-State Drain Current	$V_{GS} = -4.5V, V_{DS} = -5V$	-20	-	-	Α
9 _{FS}	Forward Transconductance	$V_{DS} = -5V, I_{D} = -3.0A$	-	7	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = -10V, V _{GS} = 0V, f = 1.0MHz	-	435	-	pF
C _{oss}	Output Capacitance		-	80	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1.500112	-	45	-	pF

Switching Characteristics (Note 2)

t _{d(on)}	Turn-On Delay Time		-	9	18	ns
t _r	Turn-On Rise Time	V _{DD} = -10V, I _D = -1A	-	11	19	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = -4.5V$, $R_{GEN} = 6\Omega$	-	15	27	ns
t _f	Turn-Off Fall Time		-	6	12	ns
Q_g	Total Gate Charge	101/ 1 0 0 1	-	4	6	nC
Q_{gs}	Gate-Source Charge	$V_{DS} = -10V, I_D = -3.0A,$ $V_{GS} = -4.5V$	-	0.8	-	nC
Q_{gd}	Gate-Drain Charge	VGS = -4.5 V	-	0.9	-	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current		-	-	-1.1	Α
V_{SD}	Drain-Source Diode Forward Voltage $V_{GS} = 0V$, $I_S = -1.1$ A (Note 2)		-	-0.8	-1.2	V
t _{rr}	Diode Reverse Recovery Time	I _F = -3.0A, dI _F /dt=100A/μs	-	17	-	ns
Q _{rr}	Diode Reverse Recovery Charge	IF= -3.0A, αΙΕ/αί=100A/μS	-	6	-	nC

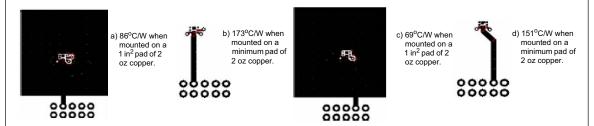
2

Electrical Characteristics $T_A = 25$ °C unless otherwise noted

- 1: R_{0JA} is determined with the device mounted on a 1 in² oz. copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0JC}is guaranteed by design while R_{0JA} is determined by the user's board design.

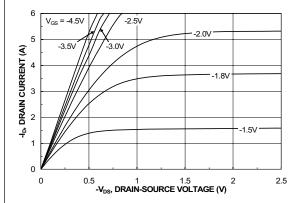
 (a) R_{0JA} = 86°C/W when mounted on a 1in² pad of 2 oz copper, 1.5" x 1.5" x 0.062" thick PCB. For single operation.

 - (b) $\rm R_{\theta JA}$ = 173°C/W when mounted on a minimum pad of 2 oz copper. For single operation.
 - (c) $R_{0JA} = 69^{\circ}$ C/W when mounted on a 1in² pad of 2 oz copper, 1.5" x 1.5" x 0.062" thick PCB, For dual operation, configured in parallel.
 - (d) $R_{\theta JA} = 151^{\circ}$ C/W when mounted on a minimum pad of 2 oz copper. For dual operation, configured in parallel.



2: Pulse Test : Pulse Width < 300us, Duty Cycle < 2.0%

Typical Characteristics



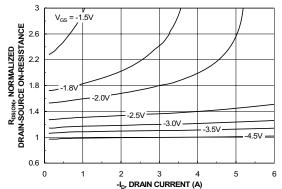
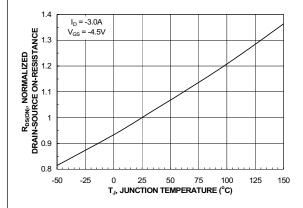


Figure 1. On-Region Characteristics

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage



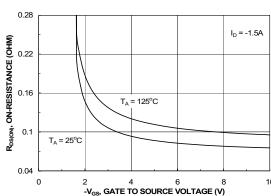
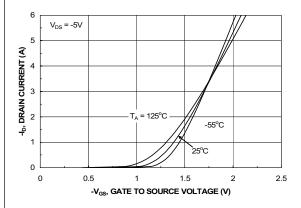


Figure 3. On-Resistance Variation with Temperature

Figure 4. On-Resistance Variation with Gate-to-Source Voltage



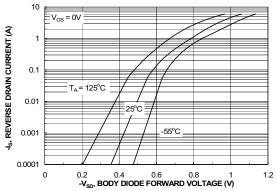


Figure 5. Transfer Characteristics

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Characteristics 700 I_D = -3.0A -V_{cs}, GATE-SOURCE VOLTAGE (V) 600 CAPACITANCE (pF) 400 300 200 -15V 10V 2 100 0 0 $\frac{2}{\mathbf{Q_g}}$, GATE CHARGE (nC) 1 8 12 16 -V_{DS}, **DRAIN TO SOURCE VOLTAGE (V)** 0 0 Figure 7. Gate Charge Characteristics Figure 8. Capacitance Characteristics SINGLEPULSE PIDKY PEAK TRANSIENT POWER (W) 10 ID, DRAIN CURRENT (A) 20 0.1 SINGLE PULSE 10 $R_{\theta,JA} = 173^{\circ}C/W$ T_A = 25°C 0.01 0.1 1 t_i, TIME (sec) 0.1 1 10 V_{DS}, **DRAIN-SOURCE VOLTAGE (V)** 0.0001 0.001 0.01 100 0.01 Figure 9. Maximum Safe Operation Area Figure 10. Single Pulse Maximum Power Dissipation

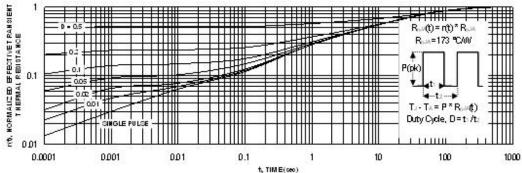
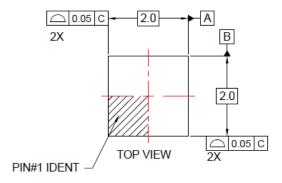
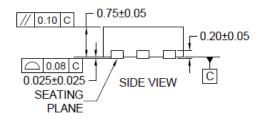


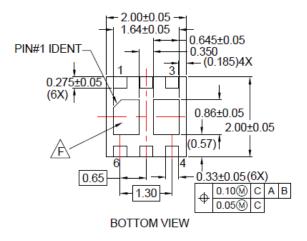
Figure 11. Transient Thermal Response Curve

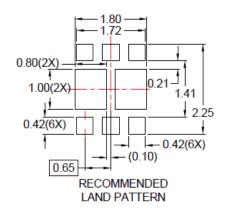
Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

Dimensional Outline and Pad Layout









NOTES:

- A. CONFORM TO JADEC REGISTRATIONS MO-229, VARIATION VCCC, EXCEPT WHERE NOTED.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-UMLP16Erev4
- F. NON-JEDEC DUAL DAP



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